Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**

****

**.010”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size = .004 x .004”**

**Backside Potential: COLLETOR**

**APPROVED BY: DK DIE SIZE .010” X .015” DATE: 9/22/21**

**MFG: SILICON SUPPLIES THICKNESS .007” P/N: MPSH10**

**DG 10.1.2**

#### Rev B, 7/1